

Abstract**SYSTEM FOR CONNECTING ELECTRONIC ASSEMBLIES**

The invention relates to a system (10) for connecting electronic assemblies (12), in particular a soldering and/or sintering system (10a), with a transport device for conveying the electronic assemblies (12) through the system (10), comprising a plurality of gas-tightly separable modules (16) for connecting the electronic assemblies (12) to one another, wherein at least one module (16) is designed as a soldering and/or sintering module (18) and one module (16) as a cooling module (20).

The invention is characterized in that between the soldering or sintering module (18) and the cooling module (20) a further module (16) is arranged that is designed as a soft cooling module (22) for cooling between a process temperature of the soldering or sintering module (18) and an intermediate temperature, in particular below a solder solidification temperature.

In a secondary aspect, it is proposed that in a module (16) designed in particular as a soldering or sintering module (18) in a gas-tightly sealable process chamber (52), in particular in the soft cooling module (22), at least one heat source (50) contactable with the electronic assemblies (12) for heating the electronic assemblies (12) and at least one cold trap (46) are arranged, the latter having in operation a surface temperature which is lower than an operating temperature of the heat source (50).

[Figure 1]